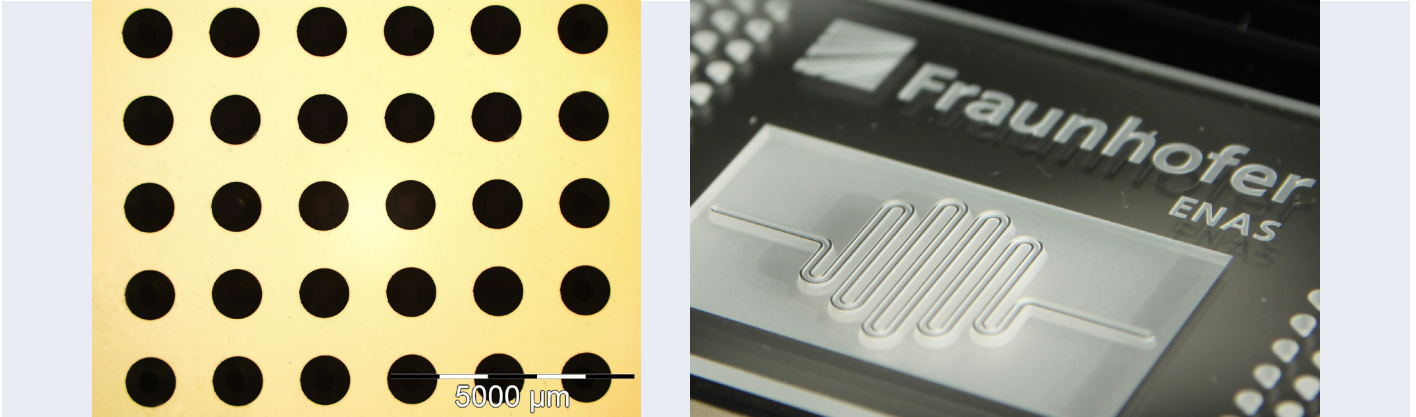


LASER MICROMACHINING OF GLASS FOR MEMS / NEMS APPLICATIONS



Contact

Fraunhofer ENAS

Fraunhofer Institute for Electronic Nano Systems
Technologie-Campus 3
09126 Chemnitz
Germany

Contact person

Prof. Dr. Thomas Otto
Phone: +49 371 45001-231
E-mail: thomas.otto@enas.fraunhofer.de

Tom Enderlein

Phone: +49 371 45001-248
E-mail: tom.enderlein@enas.fraunhofer.de

*Figures: 1 mm holes in 1 mm thick glass (left);
Glass area-ablation 500 µm deep and micro chan-
nel 250 µm wide and 100 µm deep (right)
Photo acknowledgments: Fraunhofer ENAS
All information contained in this datasheet is pre-
liminary and subject to change. Furthermore, the
described systems, materials and processes are not
commercial products.*

1. Motivation

In several applications in MEMS/NEMS ma-
nufacturing of glass, processes for dicing,
through holes, or cavity generation such as
sawing, sandblasting, etching are either not
economical, not applicable or just do not
deliver the specified quality and resolution.
Sawing, for example, exhibits no constant
cut quality due to degradation of the saw
blade, causes chipping, mechanical stress
and cracks. Furthermore it is difficult to use
for thin substrates, needs cooling fluids
and is only applicable for straight contours.
The fabrication of cavities or through holes
using etching is a time consuming process
and expensive in the development stage of
a project due to the need of cost intensive
masks. Sandblasting is a fast process, but
also needs masks, leads to damaged edges
and is difficult to apply for thin substrates.
With ultrashort pulse laser micromachining
it is possible to create any 2.5D structure in
glass with high quality, sharp edges with
no cracks, without the limitation to certain
substrate shapes and without the need of
any masks.

2. Typical Processes

- Cutting
- Through holes with variable aspect ratios
(e.g. fluidic contacts, ...)
- Channels
- Cavities
- Engraving (e.g. logos, ...)
- In-situ barcode writing in thin metal layers

3. Results and Applications

It is demonstrated that glass can be cut or
drilled in high quality with sharp, smooth
edges and no debris (Fig. 1) and without
damaging of other adjacent materials like
chromium (bright area on the left of the
small image). Furthermore, the generation
of large area cavities is as possible as struc-
turing of small micro channels as shown
in Fig. 2. Company logos or generated
barcodes can be engraved directly into the
glass surface, below the surface or in a
prior deposited metal layer without any da-
maging of the glass. All these processes are
done without any tool change in one single
process and under clean room conditions.